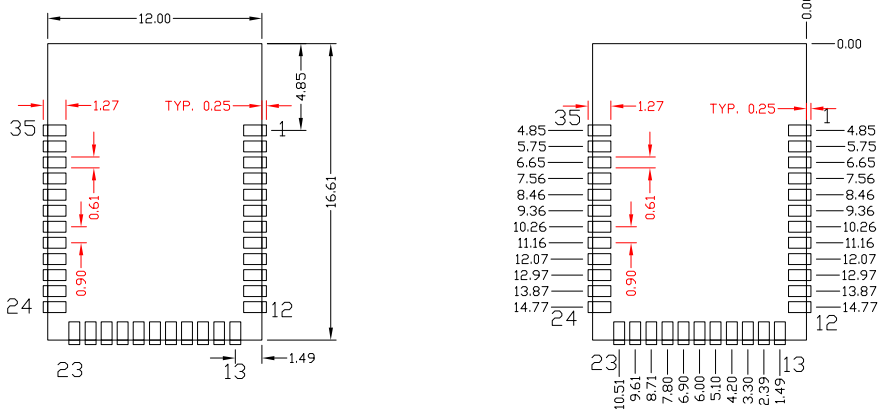
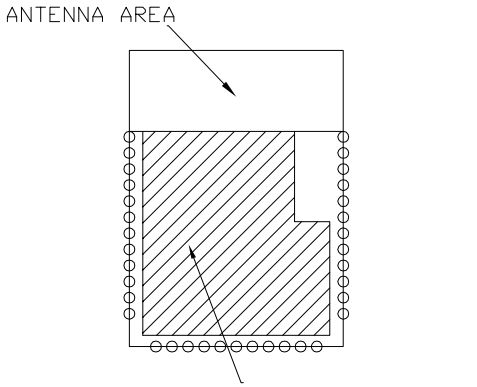
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0.1	INITIAL RELEASE	WW1850	

RECOMMEND PCB PATTERN

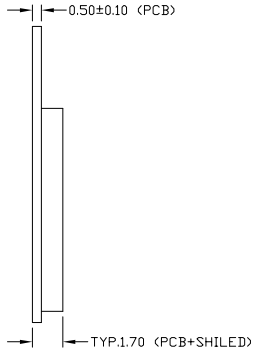


MODULE PAD ASSIGNMENT:

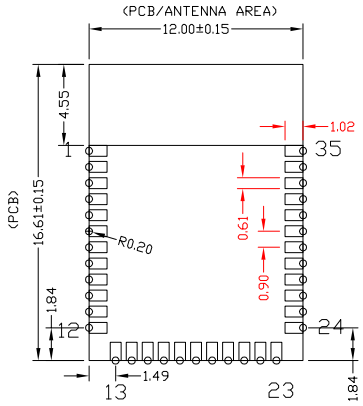
PAD1:GND
PAD2:VDD
PAD3:XRES
PAD4:P29
PAD5:P32
PAD6:P27
PAD7:P37
PAD8:P28
PAD9:P0
PAD10:P1
PAD11:P10
PAD12:P13
PAD13:GND
PAD14:P12
PAD15:P11
PAD16:P9
PAD17:P14
PAD18:P17
PAD19:P5
PAD20:P6
PAD21:P4
PAD22:P2
PAD23:P3
PAD24:XTALI_32K
PAD25:XTALO_32K
PAD26:P15
PAD27:P8
PAD28:UART_CTS_N
PAD29:UART_RTS_N
PAD30:UART_TXD
PAD31:UART_RXD
PAD32:HOST_WAKE
PAD33:DEV_WAKE
PAD34:P26
PAD35:GND



SEEN FROM TOP



SEEN FROM SIDE



SEEN FROM BOTTOM



SCALE 1:1

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN MM	DRAWN:	WW1850
TOLERANCES ON:	CHECKED	
+/- 0.15 MM	ENGRG	
ANGLES +/-0.5 DEGREE	ISSUED	

CYPRESS SEMICONDUCTOR Corp.

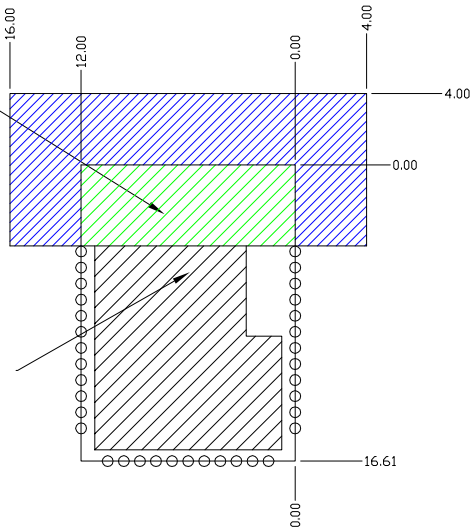
CYBT-213043-02

SIZE	REV NO	DWG NO
	0.1	

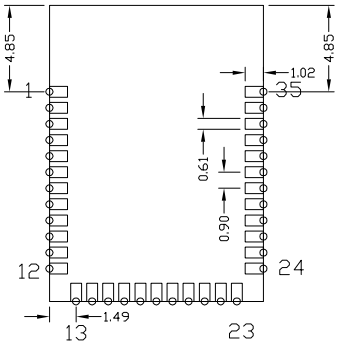
SCALE 5:1 | THE 3RD PROJECTION | SHEET: 1 OF 1

HOST PCB KEEP OUT AREA AROUND ANTENNA

1. FOR BEST RF PERFORMANCE,ADDITIONAL KEEPOUT IN BLUE HATCHED AREA ON THE HOST BOARD ON ALL LAYERS.
2. RECOMMENDATION IS TO PLACE THE BLE MODULE IN THE CORNER OF THE HOST BOARD.

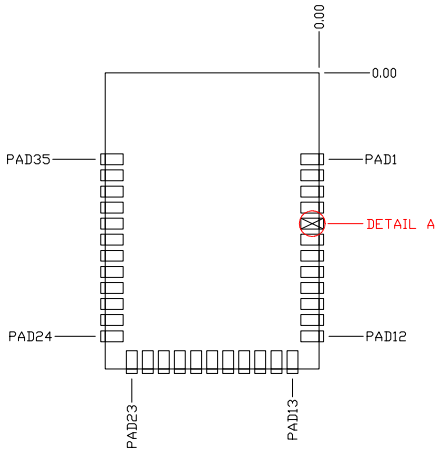


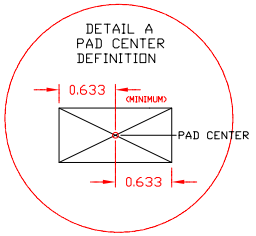
PAD DIMENSION



Solder Pad (Center of Pad)	Location (X,Y) from Orign (mm)	Dimension from Orign (mil)
1	(0.38, 4.85)	(14.96, 190.94)
2	(0.38, 5.75)	(14.96, 226.38)
3	(0.38, 6.65)	(14.96, 261.81)
4	(0.38, 7.56)	(14.96, 297.64)
5	(0.38, 8.46)	(14.96, 333.07)
6	(0.38, 9.36)	(14.96, 368.50)
7	(0.38, 10.26)	(14.96, 403.94)
8	(0.38, 11.16)	(14.96, 439.37)
9	(0.38, 12.07)	(14.96, 475.20)
10	(0.38, 12.97)	(14.96, 510.63)
11	(0.38, 13.87)	(14.96, 546.06)
12	(0.38, 14.77)	(14.96, 581.49)
13	(1.49,16.23)	(58.66, 638.98)
14	(2.39,16.23)	(94.09, 638.98)
15	(3.30,16.23)	(129.92, 638.98)
16	(4.20,16.23)	(165.35, 638.98)
17	(5.10,16.23)	(200.79, 638.98)
18	(6.00,16.23)	(236.22, 638.98)
19	(6.90,16.23)	(271.65, 638.98)
20	(7.80,16.23)	(307.09, 638.98)
21	(8.71,16.23)	(342.91, 638.98)
22	(9.61,16.23)	(378.35, 638.98)
23	(10.51,16.23)	(413.78, 638.98)
24	(11.62,14.47)	(457.48, 581.49)
25	(11.62,13.87)	(457.48, 546.06)
26	(11.62,12.97)	(457.48, 510.63)
27	(11.62,12.07)	(457.48, 475.20)
28	(11.62,11.16)	(457.48, 439.37)
29	(11.62,10.26)	(457.48, 403.94)
30	(11.62,9.36)	(457.48, 368.50)
31	(11.62,8.46)	(457.48, 333.07)
32	(11.62,7.56)	(457.48, 297.64)
33	(11.62,6.65)	(457.48, 261.81)
34	(11.62,5.75)	(457.48, 226.38)
35	(11.62,4.85)	(457.48, 190.94)

SOLDER PAD AND LOCATION





UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.20 MM ANGLES +/-0.5 DEGREE	DRAWN:	WW1850
	CHECKED	
	ENGRG	
	ISSUED	

CYPRESS SEMICONDUCTOR Corp.

CYBT-213043-02

SIZE	REV NO	DWG NO
	0.1	

SCALE 5:1 | THE 3RD PROJECTION | SHEET: 2 OF 2